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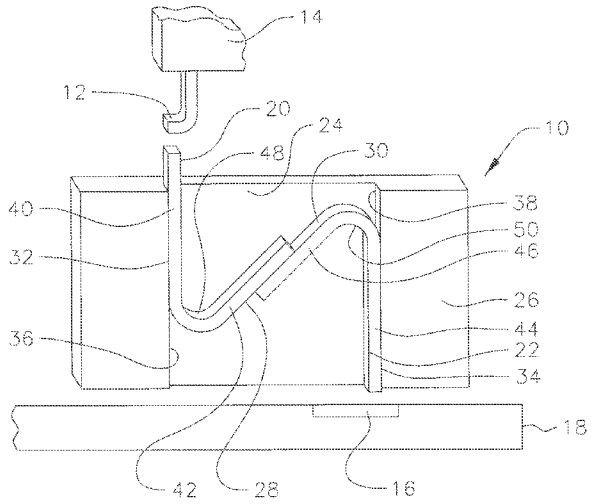
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(54) **Title:** SEMICONDUCTOR ELECTROMECHANICAL CONTACT

FIG.1



(57) **Abstract:** A compliant electrical contact assembly for interconnecting a lead or terminal of an integrated circuit having two cantilever beams positioned within a slot in a housing arranged such that a portion of the beams slide along a portion of one another and within the housing as the beams are deformed elastically in order to allow more travel and compliance without yielding or totally deforming the beam. The sliding action during deformation effectively multiplies the total compliance in the assembly above and beyond the compliance otherwise available to elastic compression of the cantilever beams.

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